

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE30H12K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

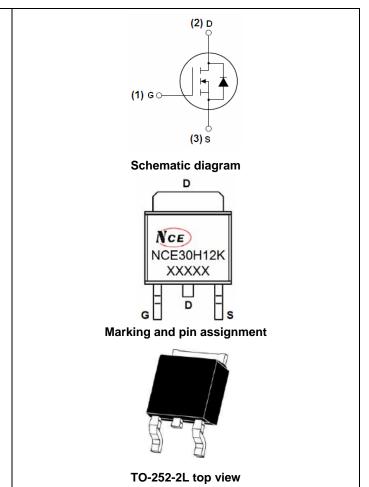
General Features

- $V_{DS} = 30V, I_D = 120A$ $R_{DS(ON)} < 4.5m\Omega @ V_{GS} = 10V$ (Typ:3.5m Ω)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED! 100% ΔVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE30H12K	NCE30H12K	TO-252-2L	-	-	-

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	Ι _D	120	А
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	84	A
Pulsed Drain Current	I _{DM}	400	A
Maximum Power Dissipation	PD	120	W
Single pulse avalanche energy (Note 5)	E _{AS}	350	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 175	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{θJC}	1.25	°C /W
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Electrical Characteristics (T_A=25 $^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA 30		-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	•		•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1	1.6	3	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	3.5	4.5	mΩ
Gate resistance	R _G	F=1.0MHz	-	1.2	-	Ω
Forward Transconductance	g fs	V _{DS} =10V,I _D =20A	50	-	-	S
Dynamic Characteristics (Note4)	•		•			
Input Capacitance	C _{lss}			4120		PF
Output Capacitance	C _{oss}	V _{DS} =25V,V _{GS} =0V, F=1.0MHz		498		PF
Reverse Transfer Capacitance	C _{rss}			456		PF
Switching Characteristics (Note 4)	•		•			
Turn-on Delay Time	t _{d(on)}		-	11	-	nS
Turn-on Rise Time	tr	V _{GS} =10V,V _{DS} =20V	-	10	-	nS
Turn-Off Delay Time	$t_{d(off)}$	R _L =0.75Ω,R _{GEN} =3Ω	-	38	-	nS
Turn-Off Fall Time	t _f		-	11	-	nS
Total Gate Charge	Qg			79		nC
Gate-Source Charge	Q _{gs}	V _{GS} =10V,V _{DS} =15V,I _D =20A		9		nC
Gate-Drain Charge	Q_gd			18		nC
Drain-Source Diode Characteristics	•		•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current (Note 2)	I _S	-		-	120	А
Reverse Recovery Time	t _{rr}	TJ = 25°C, I _F =20A	-	58	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	115	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, $t \le 10$ sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

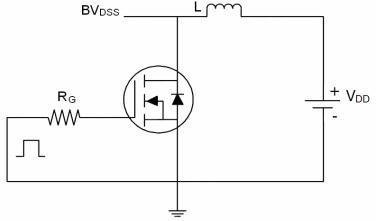
4. Guaranteed by design, not subject to production

5. EAS condition: Tj=25 $^\circ\!\mathrm{C}$,V_DD=15V,V_G=10V,L=0.5mH,Rg=25 Ω

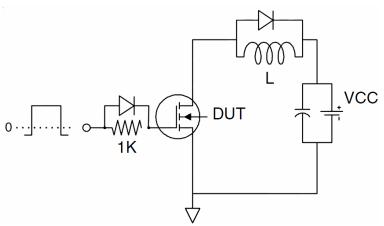


Test circuit

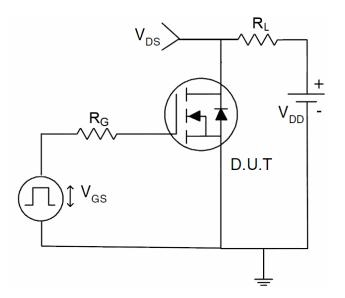
1) E_{AS} test Circuits



2) Gate charge test Circuit:

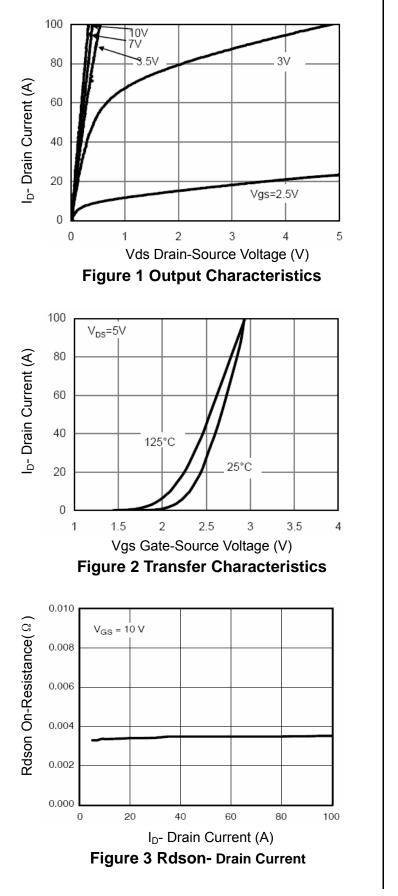


3) Switch Time Test Circuit:





Typical Electrical and Thermal Characteristics (Curves)



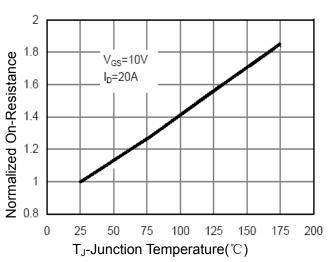
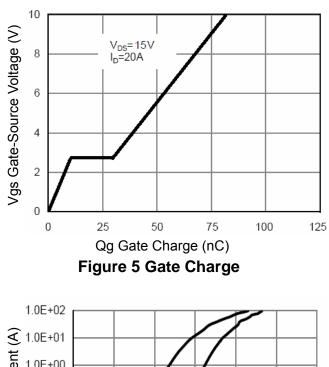
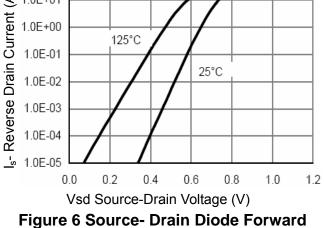


Figure 4 Rdson-Junction Temperature

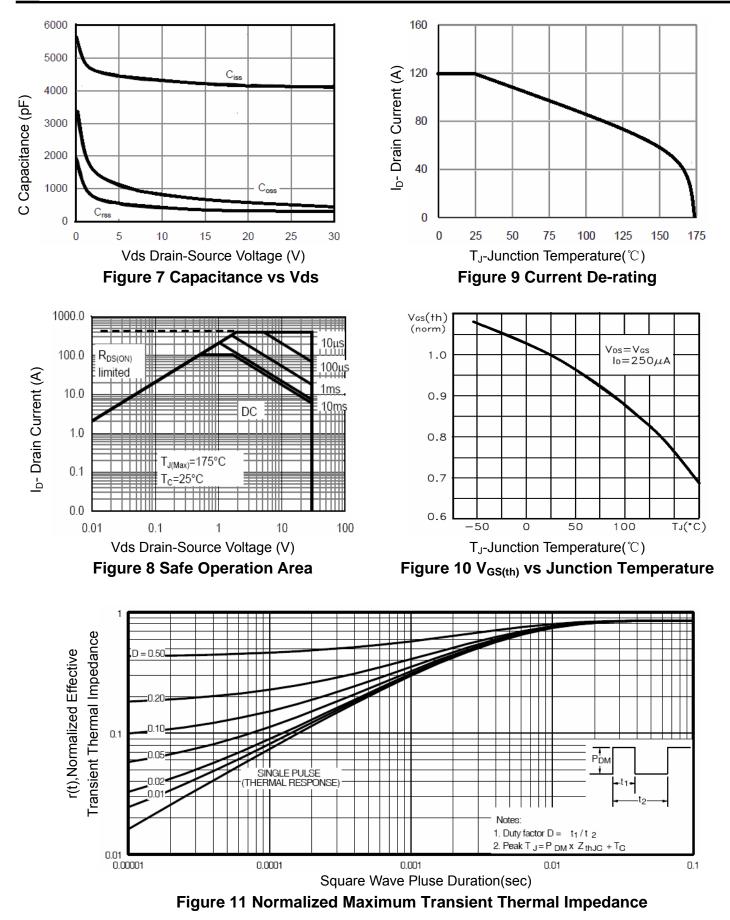






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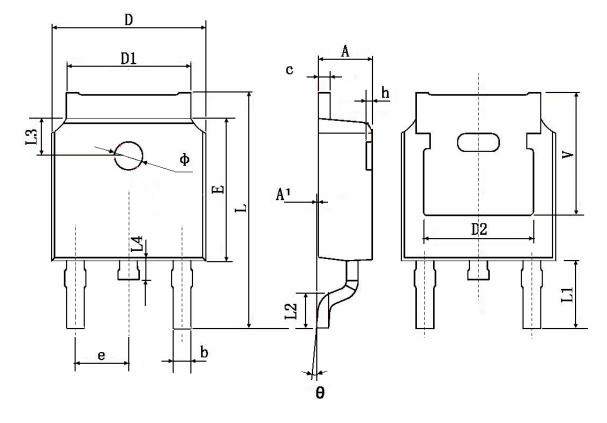
NCE30H12K





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TO-252 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.83	TYP.	0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	TYP.	0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	5.350 TYP. 0.211 TYP.			



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